

To our customers,

Old Company Name in Catalogs and Other Documents

On April 1st, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: <http://www.renesas.com>

April 1st, 2010
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

Send any inquiries to <http://www.renesas.com/inquiry>.

Notice

1. All information included in this document is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas Electronics products listed herein, please confirm the latest product information with a Renesas Electronics sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas Electronics such as that disclosed through our website.
2. Renesas Electronics does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Renesas Electronics products or technical information described in this document. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
3. You should not alter, modify, copy, or otherwise misappropriate any Renesas Electronics product, whether in whole or in part.
4. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation of these circuits, software, and information in the design of your equipment. Renesas Electronics assumes no responsibility for any losses incurred by you or third parties arising from the use of these circuits, software, or information.
5. When exporting the products or technology described in this document, you should comply with the applicable export control laws and regulations and follow the procedures required by such laws and regulations. You should not use Renesas Electronics products or the technology described in this document for any purpose relating to military applications or use by the military, including but not limited to the development of weapons of mass destruction. Renesas Electronics products and technology may not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations.
6. Renesas Electronics has used reasonable care in preparing the information included in this document, but Renesas Electronics does not warrant that such information is error free. Renesas Electronics assumes no liability whatsoever for any damages incurred by you resulting from errors in or omissions from the information included herein.
7. Renesas Electronics products are classified according to the following three quality grades: “Standard”, “High Quality”, and “Specific”. The recommended applications for each Renesas Electronics product depends on the product’s quality grade, as indicated below. You must check the quality grade of each Renesas Electronics product before using it in a particular application. You may not use any Renesas Electronics product for any application categorized as “Specific” without the prior written consent of Renesas Electronics. Further, you may not use any Renesas Electronics product for any application for which it is not intended without the prior written consent of Renesas Electronics. Renesas Electronics shall not be in any way liable for any damages or losses incurred by you or third parties arising from the use of any Renesas Electronics product for an application categorized as “Specific” or for which the product is not intended where you have failed to obtain the prior written consent of Renesas Electronics. The quality grade of each Renesas Electronics product is “Standard” unless otherwise expressly specified in a Renesas Electronics data sheets or data books, etc.
 - “Standard”: Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; and industrial robots.
 - “High Quality”: Transportation equipment (automobiles, trains, ships, etc.); traffic control systems; anti-disaster systems; anti-crime systems; safety equipment; and medical equipment not specifically designed for life support.
 - “Specific”: Aircraft; aerospace equipment; submersible repeaters; nuclear reactor control systems; medical equipment or systems for life support (e.g. artificial life support devices or systems), surgical implantations, or healthcare intervention (e.g. excision, etc.), and any other applications or purposes that pose a direct threat to human life.
8. You should use the Renesas Electronics products described in this document within the range specified by Renesas Electronics, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas Electronics shall have no liability for malfunctions or damages arising out of the use of Renesas Electronics products beyond such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of its products, semiconductor products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Further, Renesas Electronics products are not subject to radiation resistance design. Please be sure to implement safety measures to guard them against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas Electronics product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. Please use Renesas Electronics products in compliance with all applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive. Renesas Electronics assumes no liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written consent of Renesas Electronics.
12. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products, or if you have any other inquiries.

(Note 1) “Renesas Electronics” as used in this document means Renesas Electronics Corporation and also includes its majority-owned subsidiaries.

(Note 2) “Renesas Electronics product(s)” means any product developed or manufactured by or for Renesas Electronics.

H8SX Family

Output of Multiple \overline{CS} Signals through the Same Pin

Introduction

The H8SX/1663 is capable of the output of multiple \overline{CS} signals via a single pin. This application note covers an example where $\overline{CS1}$ and $\overline{CS2}$ output signals are both output via a single pin.

Target Device

H8SX/1663

Contents

1.	Specification.....	2
2.	Applicable Conditions	2
3.	Description of Modules Used	3
4.	Principles of Operation.....	7
5.	Description of Software	8
6.	Documents for Reference (Note).....	16

1. Specification

This LSI circuit is capable of the output of multiple \overline{CS} signals via a single pin. In this example, the $\overline{CS1}$ output and $\overline{CS2}$ output are both on the same pin (pin PB1) so that access to any location in the range formed by areas 1 and 2 (H'200000 – H'BFFFFFF) is selected by the \overline{CS} signal on PB1.

- An example of connection of this sample task is shown in figure 1.
- The PFCR is set so that both the $\overline{CS1}$ and $\overline{CS2}$ signals are output from pin PB1.
- In this example, one byte of data is written to H'200000 in area 1 and then H'400000 in area 2, and output of the common \overline{CS} signal from the PB1 pin is confirmed.

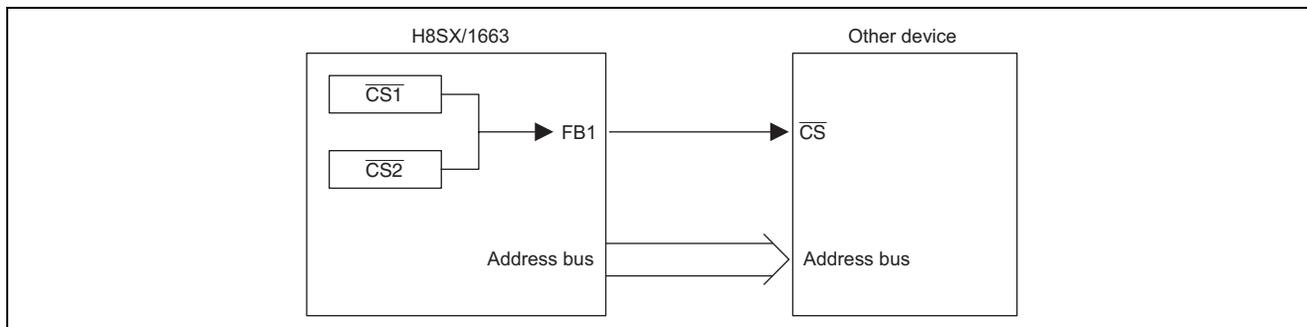


Figure 1 Example of Connection for Output of Multiple \overline{CS} Signals through the Same Pin

2. Applicable Conditions

Table 1 Applicable Conditions

Item	Description
Operating frequency	Input clock : 16 MHz
	System clock ($I\phi$) : 32MHz (input clock frequency \times 2)
	Peripheral module clock ($P\phi$) : 32 MHz (input clock frequency \times 2)
	External bus clock ($B\phi$) : 32 MHz (input clock frequency \times 2)
Operating mode	Mode 6 (MD2 = 1, MD1 = 1, MD0 = 0, MD_CLK = 0)

3. Description of Modules Used

3.1 Bus Controller

Figure 2 is a block diagram of the bus-control block.

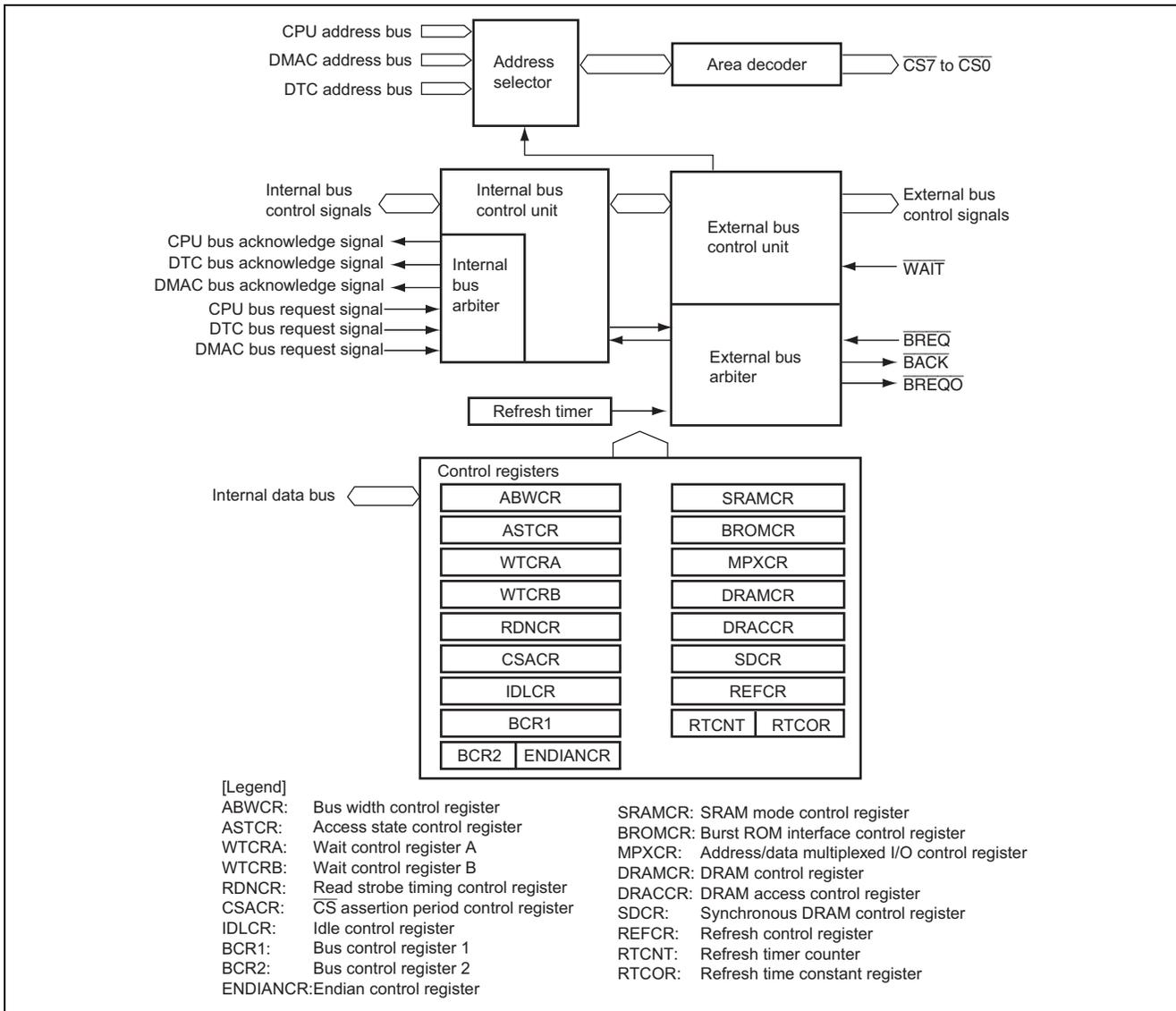


Figure 2 Block Diagram of the Bus Controller

Explanations of the functional elements shown in figure 2 are given below.

- Bus width control register (ABWCR)
 ABWCR is used to set data-bus width for all areas of external address space.
- Access state-control register (ASTCR)
 ASTCR is used to set all areas of external address space as spaces for access in two states (cycles of the bus clock) or as spaces for access in three states. Settings to enable or disable the wait states can be made at the same time.
- Wait control register B (WTCRB)
 WTCRB is used to select numbers of programmed cycles of waiting for access to all areas of external address space.
- Port function control registers 0, 2, 4, 6 (PFCR0, 2, 4, 6)
 PFCRs control the I/O ports. With the settings in this example, the $\overline{CS1}$ and $\overline{CS2}$ signals are output on pin PB1, output on the RD/\overline{WR} pin and on pins A16 to A20 is enabled, and the \overline{LHWR} output pin is set.
- Port D data direction register (PDDDR)
- Port E data direction register (PEDDR)
 DDRs are 8-bit write-only registers and used to specify bit-wise settings of input or output for the pins of the corresponding ports. In this example, pins A0 to A15 are set as output pins.

3.2 Chip Select

This LSI can output chip select signals ($\overline{CS0}$ to $\overline{CS7}$) for areas 0 to 7. The low level is output when the corresponding area of external address space is accessed.

Enabling or disabling of \overline{CSn} signal output is set by the port function control registers (PFCR).

In on-chip ROM disabled extended mode, pin $\overline{CS0}$ is placed in the output state after a reset. Pins $\overline{CS1}$ to $\overline{CS7}$ are placed in the input state after a reset and so the corresponding PFCR bits should be set to 1 if signals $\overline{CS1}$ to $\overline{CS7}$ are to be output.

In on-chip ROM enabled extended mode, pins $\overline{CS0}$ to $\overline{CS7}$ are all placed in the input state after a reset and so the corresponding PFCR bits should be set to 1 if signals $\overline{CS0}$ to $\overline{CS7}$ are to be output.

The PFCRs can specify multiple \overline{CS} outputs for most of the pins. If multiple \overline{CSn} outputs are specified for a single pin by the PFCR, the \overline{CS} to be output is generated by combining all of the specified \overline{CS} signals. In this case, areas for which the \overline{CSn} signals will be output through the same pin should have the same external bus interface settings.

Table 2 shows the system of \overline{CS} output and \overline{CS} signals

Table 2 The System of \overline{CS} Output Pins and \overline{CS} Signals

\overline{CS} Output Pin	\overline{CS} Signal	PFCR1	PFCR2
PB7	—	—	—
PB6	$\overline{CS6}$ -D	CS6SA, CS6SB = B'11	—
PB5	$\overline{CS5}$ -D	CS5SA, CS5SB = B'11	—
PB4	$\overline{CS4}$ -B	CS4SA, CS4SB = B'01	—
PB3	$\overline{CS3}$ -A	—	—
	$\overline{CS7}$ -A	CS7SA, CS7SB = B'00	—
PB2	$\overline{CS2}$ -A	—	CS2S = 0
	$\overline{CS6}$ -A	CS6SA, CS6SB = B'00	—
PB1	$\overline{CS1}$	—	—
	$\overline{CS2}$ -B	—	CS2S = 1
	$\overline{CS5}$ -A	CS5SA, CS5SB = B'00	—
	$\overline{CS6}$ -B	CS6SA, CS6SB = B'01	—
	$\overline{CS7}$ -B	CS7SA, CS7SB = B'01	—
PB0	$\overline{CS0}$	—	—
	$\overline{CS4}$ -A	CS4SA, CS4SB = B'00	—
	$\overline{CS5}$ -B	CS5SA, CS5SB = B'01	—

3.3 Division into Areas

The external address space is divided into eight areas and the bus controller executes bus control for the external address space in area units. Chip-select signals ($\overline{CS0}$ to $\overline{CS7}$) can be output for each of the areas.

Figure 3 shows how the 16-Mbyte address space is divided into areas. In this sample task, settings are made so that access to either area 1 or area 2 produces \overline{CS} signal output on the same pin (pin PB1).

H' 000000	Area 0 (2 Mbytes)
H' 1FFFFFF H' 200000	Area 1 (2 Mbytes)
H' 3FFFFFF H' 400000	Area 2 (8 Mbytes)
H' BFFFFFF H' C00000	Area 3 (2 Mbytes)
H' DFFFFFF H' E00000	Area 4 (1 Mbyte)
H' EFFFFFF H' F00000	Area 5 (8 Kbytes–1 Mbyte)
H' FFDFFF H' FFE000	Area 6 (256 bytes–8 Kbytes)
H' FFEFFF H' FFFF00	Area 7 (256 bytes)
H' FFFF00 H' FFFFFFF	

Figure 3 Division into Areas

4. Principles of Operation

Timing when the \overline{CS} signals for areas 1 and 2 are output through a single pin is shown in figure 4.

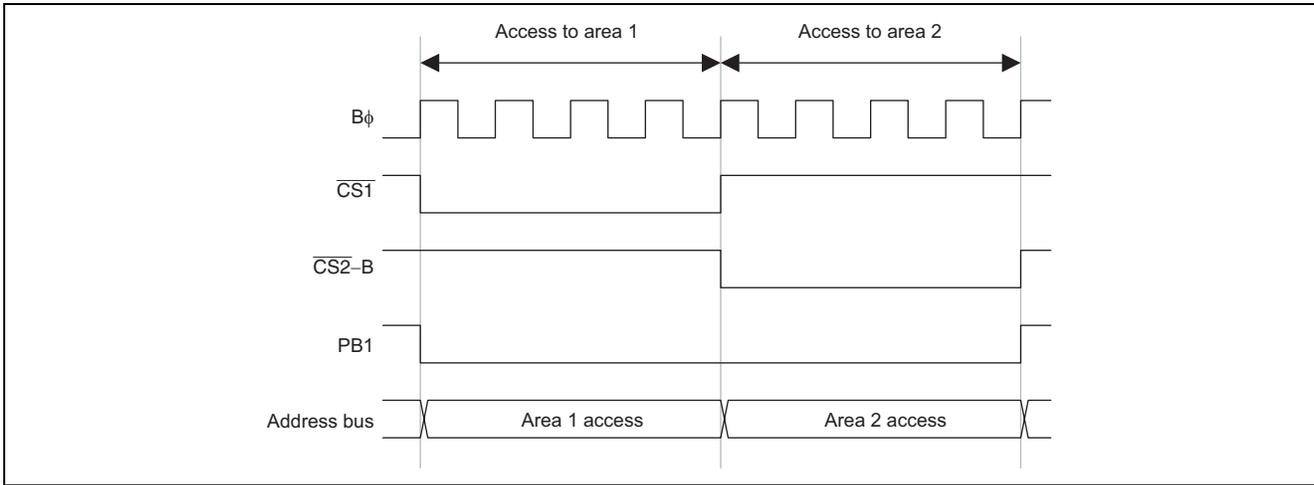


Figure 4 Timing when Multiple \overline{CS} Signals are Output through a Single Pin

5. Description of Software

5.1 Operating Environment

Table 3 Operating Environment

Item	Details
Development tool	High-performance Embedded Workshop Ver.4.01.01
C/C++ compiler	H8S, H8/300 Series C/C++ Compiler, ver. 6.01.02 (manufactured by Renesas Technology)
Compiler options	-cpu = h8sxa:24:md, -code = machinecode, -optimize = 1, -regparam = 3 -speed = (register, shift, struct, expression)

Table 4 Section Settings

Address	Section Name	Description
H'001000	P	Program area
H'200000	BCS1	Area1
H'400000	BCS2	Area2

Table 5 Vector Table for Exception Processing

Exception Processing Source	Vector No.	Vector address	Function to interrupt destination
Reset	0	H'000000	init

5.2 List of Functions

Table 6 Functions in File main.c

Function Name	Function
init	Initialization routine Sets the CCR and configures the clocks, releases the required modules from the module stop mode, and calls the main function.
main	Main routine Calls the Bsclnit function; writes one byte to the first addresses of areas 1 and 2.
Bsclnit	Initialization of areas 1 and 2; settings for output of the $\overline{CS1}$ and $\overline{CS2}$ signals on pin PB1.

5.3 RAM Usage

Table 7 RAM Usage

Type	Variable Name	Description	Used in
unsigned char	area1	First address of area 1	main
unsigned char	area2	First address of area 2	main

5.4 Description of Functions

5.4.1 init Function

1. Functional overview

The initialization routine releases the required modules from module-stop mode, configures the clocks, and calls the main function.

2. Arguments

None

3. Return value

None

4. Description of internal registers used

The internal registers used in this sample task are described below. Note that the settings shown below are not the initial values but the values used in this sample task.

- Mode control register (MDCR) Number of bits: 16 Address: H'FFFDC0

Bit	Bit Name	Setting	R/W	Description
15	MDS7	Undefined*	R	Indicates the value set by a mode pin (MD3). When MDCR is read, the input level on the MD3 pin is latched. The latching is released by a reset.
11	MDS3	Undefined*	R	Mode Select 3 to 0
10	MDS2	Undefined*	R	These bits indicate the operating mode selected by mode pins (MD2 to MD0; see table 8). When MDCR is read, the signal levels input on pins MD2 to MD0 are latched into these bits. The latching is released by a reset.
9	MDS1	Undefined*	R	
8	MDS0	Undefined*	R	

Note: * Determined by the setting on pins MD0 to MD3.

Table 8 Settings of Bits MDS3 to MDS0

MCU Operating Mode	Mode Pins			MDCR			
	MD2	MD1	MD0	MDS3	MDS2	MDS1	MDS0
2	0	1	0	1	1	0	0
4	1	0	0	0	0	1	0
5	1	0	1	0	0	0	1
6	1	1	0	0	1	0	1
7	1	1	1	0	1	0	0

- System clock control register (SCKCR) Number of bits: 16 Address: H'FFFDC4

Bit	Bit Name	Setting	R/W	Description
10	ICK2	0	R/W	System Clock ($I\phi$) Select
9	ICK1	0	R/W	These bits select the frequency of the system clock, which is provided to the CPU, DMAC, and DTC. 001: Input clock \times 2
8	ICK0	1	R/W	
6	PCK2	0	R/W	Peripheral Module Clock ($P\phi$) Select
5	PCK1	0	R/W	These bits select the frequency of the peripheral module clock. 001: Input clock \times 2
4	PCK0	1	R/W	
2	BCK2	0	R/W	External Bus Clock ($B\phi$) Select
1	BCK1	0	R/W	These bits select the frequency of the external bus clock. 001: Input clock \times 2
0	BCK0	1	R/W	

- MSTPCRA, B and C control module stop mode. Setting a bit to 1 makes the corresponding module enter the module-stop state, while clearing the bit to 0 releases the module from module stop state.

- Module stop control register A (MSTPCRA) Number of bits: 16 Address: H'FFFDC8

Bit	Bit Name	Setting	R/W	Description
15	ACSE	0	R/W	All-Module-Clock-Stop Mode Enable Enables/disables all-module-clock-stop mode for reducing current consumption by stopping operation of the bus controller and I/O ports when the CPU executes the SLEEP instruction after the module stop state has been set for all of the on-chip peripheral modules controlled by MSTPCR. 0: Disables all-module-clock-stop mode. 1: Enables all-module-clock-stop mode.
13	MSTPA13	1	R/W	DMA controller (DMAC)
12	MSTPA12	1	R/W	Data transfer controller (DTC)
9	MSTPA9	1	R/W	8-bit timer unit (TMR_3 and TMR_2)
8	MSTPA8	1	R/W	8-bit timer unit (TMR_1 and TMR_0)
5	MSTPA5	1	R/W	D/A converter (channels 1 and 0)
3	MSTPA3	1	R/W	A/D converter (unit 0)
0	MSTPA0	1	R/W	16-bit timer pulse unit (TPU channels 5 to 0)

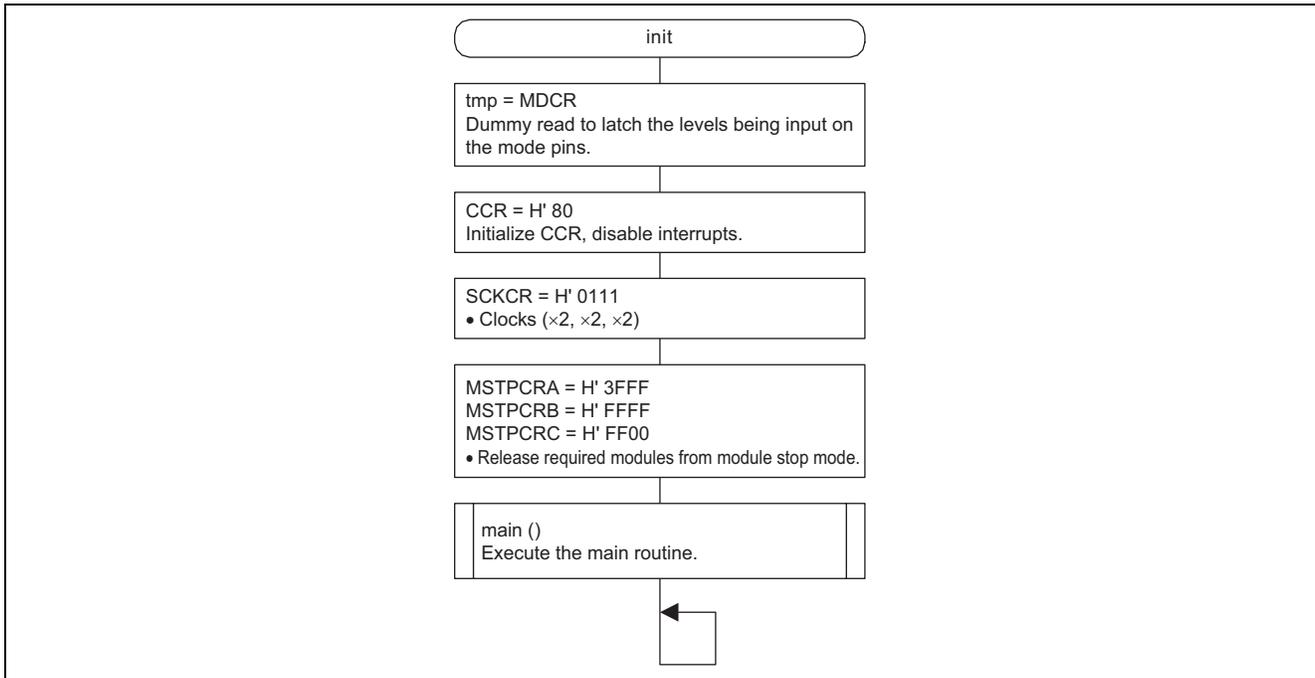
- Module stop control register B (MSTPCRB) Number of bits: 16 Address: H'FFFDCA

Bit	Bit Name	Setting	R/W	Description
15	MSTPB15	1	R/W	Programmable pulse generator (PPG)
12	MSTPB12	1	R/W	Serial communications interface_4 (SCI_4)
10	MSTPB10	1	R/W	Serial communications interface_2 (SCI_2)
9	MSTPB9	1	R/W	Serial communications interface_1 (SCI_1)
8	MSTPB8	1	R/W	Serial communications interface_0 (SCI_0)
7	MSTPB7	1	R/W	I ² C bus Interface 1 (IIC_1)
6	MSTPB6	1	R/W	I ² C bus Interface 0 (IIC_0)

- Module stop control register C (MSTPCRC) Number of bits: 16 Address: H'FFDCC

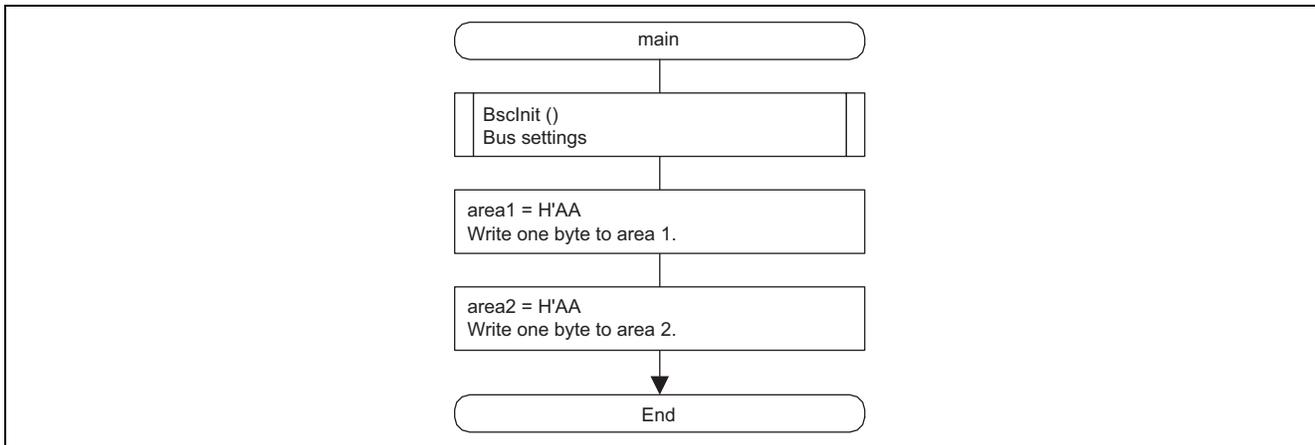
Bit	Bit Name	Setting	R/W	Description
15	MSTPC15	1	R/W	Serial communications interface_5 (SCI_5 and IrDA)
14	MSTPC14	1	R/W	Serial communications interface_6 (SCI_6)
13	MSTPC13	1	R/W	8-bit timer unit (TMR_4 and TMR_5)
12	MSTPC12	1	R/W	8-bit timer unit (TMR_6 and TMR_7)
11	MSTPC11	1	R/W	Universal serial bus interface (USB)
10	MSTPC10	1	R/W	Cyclic redundancy check module
4	MSTPC4	0	R/W	On-chip RAM_4 (H'FF2000 to H'FF3FFF)
3	MSTPC3	0	R/W	On-chip RAM_3 (H'FF4000 to H'FF5FFF)
2	MSTPC2	0	R/W	On-chip RAM_2 (H'FF6000 to H'FF7FFF)
1	MSTPC1	0	R/W	On-chip RAM_1 (H'FF8000 to H'FF9FFF)
0	MSTPC0	0	R/W	On-chip RAM_0 (H'FFA000 to H'FFBFFF)

5. Flowchart



5.4.2 main Function

1. Functional overview
Calls function BscInit and writes one byte to the first addresses of areas 1 and 2.
2. Arguments
None
3. Return value
None
4. Description of internal registers used
None
5. Flowchart



5.4.3 Function Bsclnit

1. Functional outline

Initializes areas 1 and 2; sets up output of $\overline{CS1}$ and $\overline{CS2}$ signals on pin PB1.

2. Arguments

None

3. Return value

None

4. Description of internal registers used

The internal registers used in this sample task are described below. Note that the settings shown below are not the initial values but the values used in this sample task.

- Port D data direction register (PDDDR) Number of bits: 8 Address: H'FFFB8C
Function: PDDDR sets pins PD7 to 0 as output pins for address output.
Value: H'FF
- Port E data direction register (PEDDR) Number of bits: 8 Address: H'FFFB8D
Function: PEDDR sets pins PE7 to 0 as output pins for address output.
Value: H'FF
- Bus width control register (ABWCR) Number of bits: 16 Address: H'FFFD84
Function: ABWCR sets areas 7 to 0 as spaces for 16-bit access.
Value: H'00FF
- Access state-control register (ASTCR) Number of bits: 16 Address: H'FFFD86
Function: ASTCR sets areas 7 to 0 as spaces for access in three states (cycles of the bus clock).
Value: H'FF00
- Wait control register B (WTCRB) Number of bits: 16 Address: H'FFFD8A
Function: WTCRB sets the number for programmed waiting. Seven states (cycles of the bus clock) are inserted for access to area 3.
Value: H'0770
- Read strobe timing control register (RDNCR) Number of bits: 16 Address: H'FFFD8C
Function: For read access to areas 7 to 0, RDNCR sets the timing for the negation of \overline{RD} at the end of read cycles.
Value: H'0000
- Port function control register 0 (PFCR0) Number of bits: 8 Address: H'FFFBC0

Bit	Bit Name	Setting	Description
7	CS7E	0	CS7–CS0 Enable
6	CS6E	0	These bits select enabling or disabling of the corresponding \overline{CSn} output pins.
5	CS5E	0	
4	CS4E	0	
3	CS3E	0	0: Setting for an I/O port pin 1: Setting for a \overline{CSn} output pin (n=7 – 0)
2	CS2E	1	
1	CS1E	1	
0	CS0E	0	

Output of Multiple \overline{CS} Signals through the Same Pin

- Port function control register 2 (PFCR2) Number of bits: 8 Address: H'FFFBC2

Bit	Bit Name	Setting	Description
6	CS2S	1	$\overline{CS2}$ Output Pin Select Specifies the output pin for $\overline{CS2}$ when $\overline{CS2}$ output is enabled. 0: Specifies pin PB2 as the $\overline{CS2}$ -A output pin. 1: Specifies pin PB1 as the $\overline{CS2}$ -B output pin.
2	RDWRE	1	RD/ \overline{WR} Output Enable 0: Output of RD/ \overline{WR} is disabled. 1: Output of RD/ \overline{WR} is enabled.

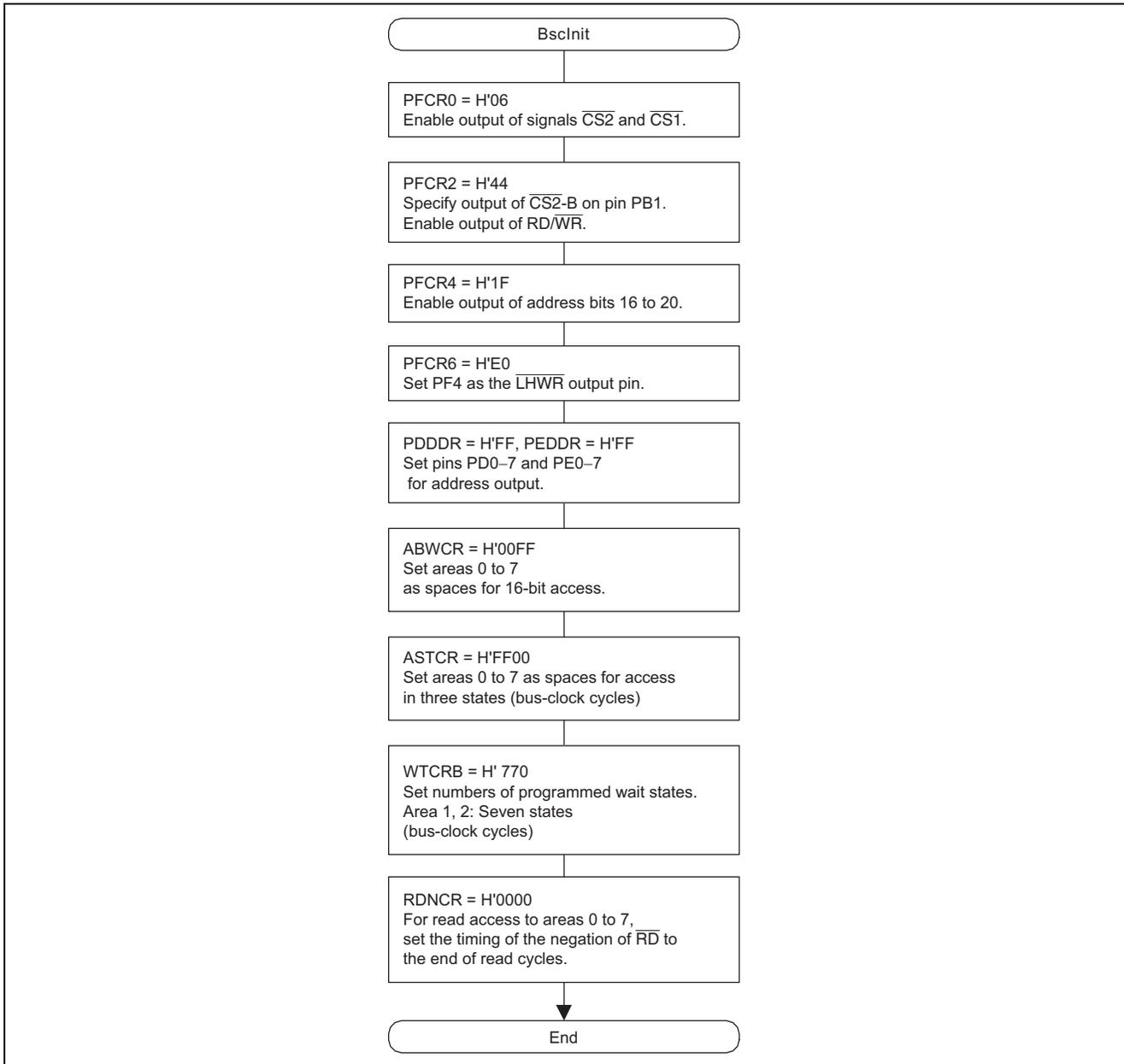
- Port function control register 4 (PFCR4) Number of bits: 8 Address: H'FFFBC4

Bit	Bit Name	Setting	Description
4	A20E	1	Address A20 Enable 0: Disables the A20 output. 1: Enables the A20 output.
3	A19E	1	Address A19 Enable 0: Disables the A19 output. 1: Enables the A19 output.
2	A18E	1	Address A18 Enable 0: Disables the A18 output. 1: Enables the A18 output.
1	A17E	1	Address A17 Enable 0: Disables the A17 output. 1: Enables the A17 output.
0	A16E	1	Address A16 Enable 0: Disables the A16 output. 1: Enables the A16 output.

- Port function control register 6 (PFCR6) Number of bits: 8 Address: H'FFFBC6

Bit	Bit Name	Setting	Description
6	LHWROE	1	\overline{LHWR} Output Enable 0: Sets PA4 as an I/O port pin 1: Sets PF4 as the \overline{LHWR} output pin

5. Flowchart



6. Documents for Reference (Note)

- Hardware Manual
H8SX/1663 Group Hardware Manual
The most up-to-date version of this document is available on the Renesas Technology Website.
- Technical News/Technical Update
The most up-to-date information is available on the Renesas Technology Website.

Website and Support

Renesas Technology Website

<http://www.renesas.com/>

Inquiries

<http://www.renesas.com/inquiry>

csc@renesas.com

Revision Record

Rev.	Date	Description	
		Page	Summary
1.00	Aug.23.07	—	First edition issued

Notes regarding these materials

1. This document is provided for reference purposes only so that Renesas customers may select the appropriate Renesas products for their use. Renesas neither makes warranties or representations with respect to the accuracy or completeness of the information contained in this document nor grants any license to any intellectual property rights or any other rights of Renesas or any third party with respect to the information in this document.
2. Renesas shall have no liability for damages or infringement of any intellectual property or other rights arising out of the use of any information in this document, including, but not limited to, product data, diagrams, charts, programs, algorithms, and application circuit examples.
3. You should not use the products or the technology described in this document for the purpose of military applications such as the development of weapons of mass destruction or for the purpose of any other military use. When exporting the products or technology described herein, you should follow the applicable export control laws and regulations, and procedures required by such laws and regulations.
4. All information included in this document such as product data, diagrams, charts, programs, algorithms, and application circuit examples, is current as of the date this document is issued. Such information, however, is subject to change without any prior notice. Before purchasing or using any Renesas products listed in this document, please confirm the latest product information with a Renesas sales office. Also, please pay regular and careful attention to additional and different information to be disclosed by Renesas such as that disclosed through our website. (<http://www.renesas.com>)
5. Renesas has used reasonable care in compiling the information included in this document, but Renesas assumes no liability whatsoever for any damages incurred as a result of errors or omissions in the information included in this document.
6. When using or otherwise relying on the information in this document, you should evaluate the information in light of the total system before deciding about the applicability of such information to the intended application. Renesas makes no representations, warranties or guaranties regarding the suitability of its products for any particular application and specifically disclaims any liability arising out of the application and use of the information in this document or Renesas products.
7. With the exception of products specified by Renesas as suitable for automobile applications, Renesas products are not designed, manufactured or tested for applications or otherwise in systems the failure or malfunction of which may cause a direct threat to human life or create a risk of human injury or which require especially high quality and reliability such as safety systems, or equipment or systems for transportation and traffic, healthcare, combustion control, aerospace and aeronautics, nuclear power, or undersea communication transmission. If you are considering the use of our products for such purposes, please contact a Renesas sales office beforehand. Renesas shall have no liability for damages arising out of the uses set forth above.
8. Notwithstanding the preceding paragraph, you should not use Renesas products for the purposes listed below:
 - (1) artificial life support devices or systems
 - (2) surgical implantations
 - (3) healthcare intervention (e.g., excision, administration of medication, etc.)
 - (4) any other purposes that pose a direct threat to human life
 Renesas shall have no liability for damages arising out of the uses set forth in the above and purchasers who elect to use Renesas products in any of the foregoing applications shall indemnify and hold harmless Renesas Technology Corp., its affiliated companies and their officers, directors, and employees against any and all damages arising out of such applications.
9. You should use the products described herein within the range specified by Renesas, especially with respect to the maximum rating, operating supply voltage range, movement power voltage range, heat radiation characteristics, installation and other product characteristics. Renesas shall have no liability for malfunctions or damages arising out of the use of Renesas products beyond such specified ranges.
10. Although Renesas endeavors to improve the quality and reliability of its products, IC products have specific characteristics such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Please be sure to implement safety measures to guard against the possibility of physical injury, and injury or damage caused by fire in the event of the failure of a Renesas product, such as safety design for hardware and software including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other applicable measures. Among others, since the evaluation of microcomputer software alone is very difficult, please evaluate the safety of the final products or system manufactured by you.
11. In case Renesas products listed in this document are detached from the products to which the Renesas products are attached or affixed, the risk of accident such as swallowing by infants and small children is very high. You should implement safety measures so that Renesas products may not be easily detached from your products. Renesas shall have no liability for damages arising out of such detachment.
12. This document may not be reproduced or duplicated, in any form, in whole or in part, without prior written approval from Renesas.
13. Please contact a Renesas sales office if you have any questions regarding the information contained in this document, Renesas semiconductor products, or if you have any other inquiries.